



Macromelt

## MACROMELT OM 648 Circuit Board Protection Product

**MACROMELT OM 648** circuit board protection product provides good adhesion and is UV stable at operating temperature -40 to 125°C, sealing and protecting electronics from moisture, mechanical damage and heat. **MACROMELT OM 648** encapsulants cure in seconds by cooling, reducing cost by more than 50% through eliminating curing ovens and lights. Suitable for the automotive, RFID, consumer electronics, photovoltaic and the aerospace industries.

Low-pressure molding is the solution to production issues associated with traditional high-pressure injection molding over sensitive electronic components or circuit boards. The polyamide hot melt adhesive material may actually be used to mold-in mounting studs or eyes, eliminate injection molded housings and covers, and replace epoxy potting operations all in one simple process. The materials also provide great strain relief in molded grommets and connectors.



Excellence is our Passion

## MACROMELT OM 648 Circuit Board Protection Product

### Target Applications

- Photovoltaic junction boxes and connectors
- LED lighting
- RFID tags
- Industrial sensors
- General electronics used in outdoor environments

### Macromelt Advantages

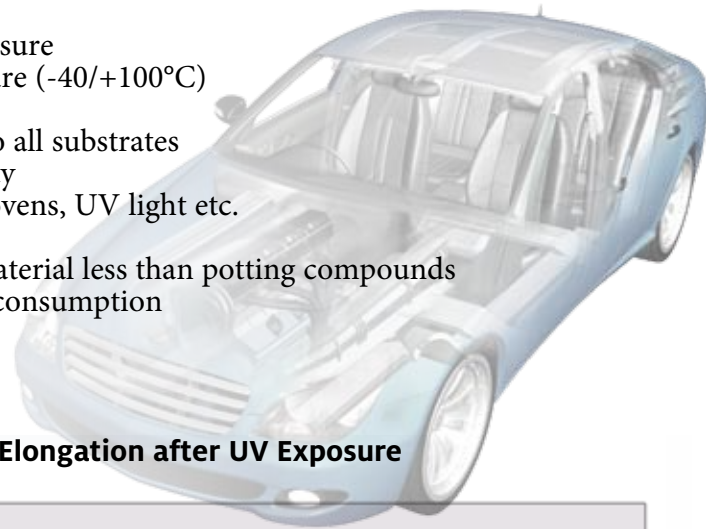
- Complete watertight encapsulation
- Fast cycle time (15-45 seconds)
- Low capital equipment costs
- Safe, 1-component, UL 94-V-0 Approved
- Low pressure and high speed molding for electronics encapsulation

### MACROMELT OM 648

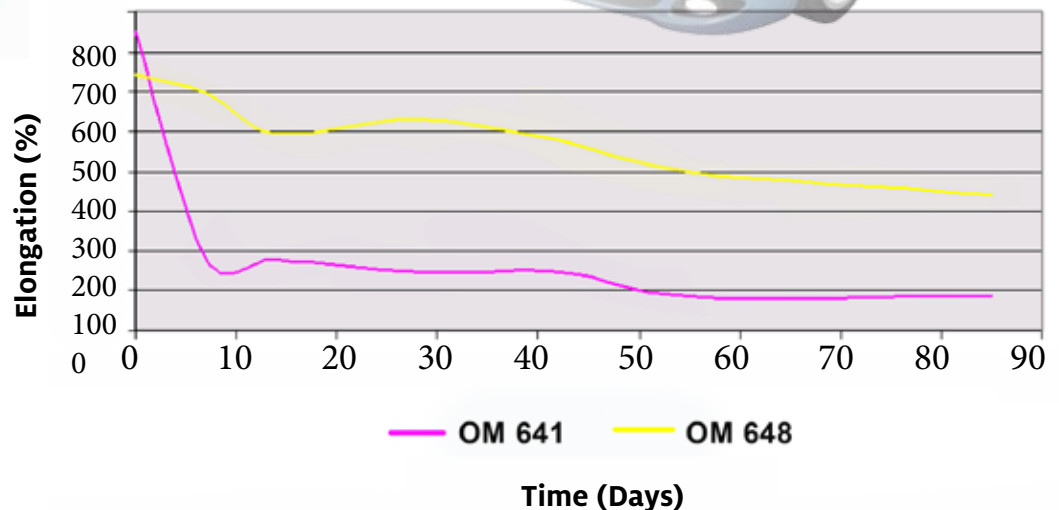
**Description:** UV stable low pressure molding encapsulant based on Henkel's polyamide hot melt technology

### Key Benefits:

- Low application pressure
- Operating temperature (-40/+100°C)
- UL rating of 94-V-0
- Excellent adhesion to all substrates
- Extended UV stability
- No need for curing ovens, UV light etc.
- Recyclable resins
- Specific gravity of material less than potting compounds
- Savings on material consumption



Elongation after UV Exposure



The tensile properties of OM 648 decreased by about 35% over the 80 days accelerated test, while the base material OM 641 decreased 85% in under 10 days.

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